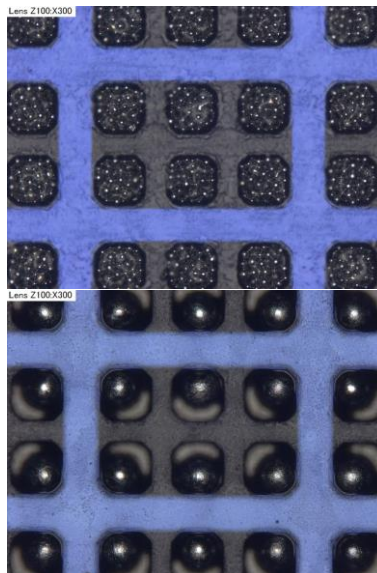


## **SHENMAO Introduces BGA and Micro BGA Bumping Solder Paste**



SHENMAO Bumping Solder Paste PF608-PI-21 (Sn/Ag4.0/Cu0.5/x) and PF606-P-BS1 (Sn/Ag3.0/Cu0.5/x) aim to decrease voids in wafer bumping process. SHENMAO applications engineers focused on developing the Bumping Solder Paste Formula with excellent stencil printing transfer rate and the lowest Void (<10%) to optimize manufacturing process performance. The world's largest IC Packaging and Test Service OSAT utilize SHENMAO Bumping Solder Paste in production.

As the World's Major Solder Materials Provider, SHENMAO produces SMT Solder Paste, Wave Solder Bar, Solder Wire and Flux, Solder Preforms, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux and PV Ribbon.

For more information, please contact:

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